

EPO-TEK® T7139 Technical Data Sheet For Reference Only Glob Top Epoxy

Recommended Cure: 150°C / 1 Hour

Minimum Alternative Cure(s): May not achieve performance properties listed below 150°C / 30 Minutes 125°C / 60 Minutes

Date: July 2019 Rev: VIII No. of Components: Two Mix Ratio by Weight: 10:1 Specific Gravity: Part A: 1.31 Part B: 1.34 Pot Life: 1 Day Shelf Life- Bulk: One year at room temperature Shelf Life- Syringe: Six months at -40°C NOTES:

• Container(s) should be kept closed when not in use.

• Filled systems should be stirred thoroughly before mixing and prior to use.

• Performance properties (rheology, conductivity, others) of the product may vary from those stated on the data sheet when bi-pak/syringe packaging or post-processing of any kind is performed. Epoxy's warranties shall not apply to any products that have been reprocessed or repackaged from Epoxy's delivered status/container into any other containers of any kind, including but not limited to syringes, bi-paks, cartridges, pouches, tubes, capsules, films or other packages.

Product Description: EPO-TEK® T7139 is a two component, electrically insulating, encapsulating epoxy designed for semiconductor glob top applications and package assembly.

<u>Typical Properties:</u> Cure condition: 150°C / 1 Hour Different batches, conditions & applications yield differing results. Data below is not guaranteed. To be used as a guide only, not as a specification. * denotes test on lot acceptance basis

PHYSICAL PROPERTIES:			
* Color (before cure):		Part A: Black	Part B: Tan
* Consistency:		Smooth paste	
* Viscosity (23°C) @ 50 rpm:		5,000 - 7,000	cPs
Thixotropic Index:		2.5	
* Glass Transition Temp:		≥ 90	°C (Dynamic Cure: 20-200°C/ISO 25 Min; Ramp -10-200°C @20°C/Min)
Coefficient of Thermal Expansion (CTE):			
	Below Tg:	30	x 10 ⁻⁶ in/in°C
	Above Tg:	76	x 10 ⁻⁶ in/in°C
Shore D Hardness:	-	86	
Lap Shear @ 23°C:		2,000	psi
Die Shear @ 23°C:		≥ 10	Kg 3,556 psi
Degradation Temp:		438	°Č
Weight Loss:			
_	@ 200°C:	0.19	%
	@ 250°C:	0.34	%
	@ 300°C:	0.48	%
Suggested Operating Temperature: < 350		< 350	°C (Intermittent)
Storage Modulus:		598,884	psi
* Particle Size:		≤ 50	microns
ELECTRICAL AND THERMAL PROPERTIES:			
Thermal Conductivity:		0.4	W/mK
Volume Resistivity @ 23°C:		≥ 3 x 10 ¹²	Ohm-cm
Dielectric Constant (1KHz):		3.39	
Dissipation Factor (1KHz):		0.006	
OPTICAL PROPERTIES @ 23°C:			
		0.040/ @ 400	
Spectral Transmission:		< 0.01% @ 400	nm
		< 1% @ 900	nm
Defective ladeur		< 5% @ 2000	nm
Refractive Index:		N/A	

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EPO-TEK® T7139 Advantages & Suggested Application Notes:

- A pot life of at least one day is mass production friendly and convenient for consecutive manufacturing shifts.
- Its thixotropic nature allows for dispensing "domes or hemispheres" directly over the IC without the need for using a dam or cavity to control flow.
- Suggested applications:
 - o Semiconductor:
 - Glob top encapsulant for COB die attach.
 - Plastic semiconductor package filling instead of traditional epoxy transfer molding compound.
 - Electronic/PCB: general protection of SMDs.
 - Opto-electronics: black and opaque epoxy for adhesive and sealing applications while blocking IR and VIS light.
- In some cases, it is advantageous to pre-warm the epoxy < 50°C in order to decrease its thixotropic nature, while increasing capillary and flow rate.
- Low CTE makes it ideal for keeping stresses to a minimum.